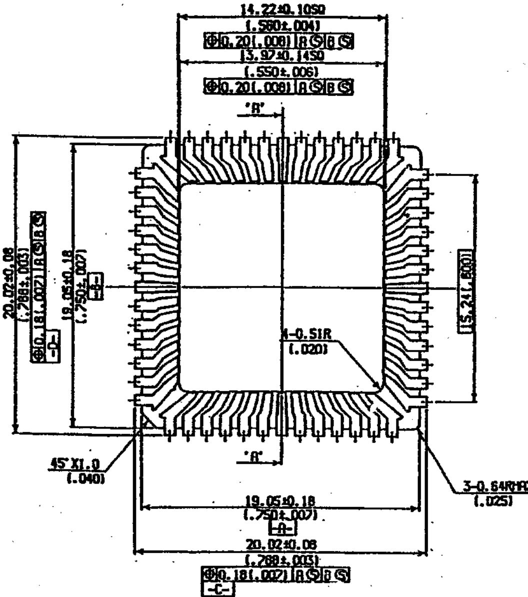
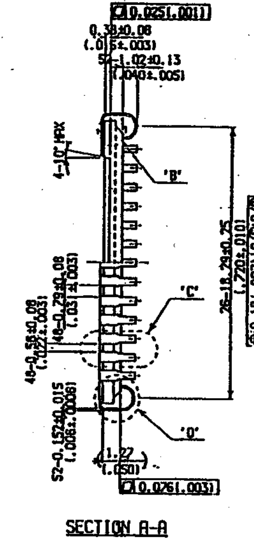
SSM P/N CQJ05205

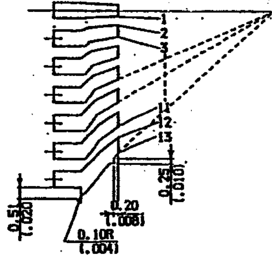
NOTES

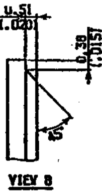
1. MATERIALS
   CERAMIC TO OPAQUE, 90-94% Al_2O_3.
   SOLDER GLASS TO BE 7583.
   MAX PULLBACK TO BE 0.25(.010)
   FROM CERMIC EDGE.
   DIE ATTACH AREA TO BE Au 120
   MICROINCH MIN.
   LEAD FRAME TO BE ALLOY 42 OR
   TYPE B MIL 38510 PARAGRAPH
   3.5.6.1. WITH ALUMINIUM
   BOND PADS 100 MICROINCH THICK.
2. THERE WILL BE NO UNSUPPORTED
   BOND PADS GRETER THAN 0.25(.010)
3. ADJACENT BOND PADS MUST BE
   CO-PLANER WITHIN 0.15(.006).
   TOTAL CO-PLANARITY NO GRATER
   THAN 0.25(.010).
4. THERE WILL BE NO NICKS, CUTS
   OR GLASS IN THE BOND RADIUS
5. MINIMIM INTERNAL METAL SEPARATOIN,
   OTHER THAN BOND FINGERS TO BE 0.13(.005)



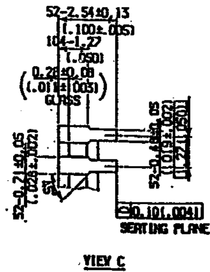


No	ANGLE
1	2.18°
2	5.25°
3	9.58°
4	12.59°
5	16.78°
6	19.68°
7	23.70°
8	26.47°
9	30.24°
10	32.83°
11	36.36°
12	38.76°
13	42.02°

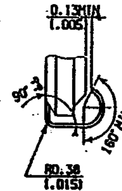


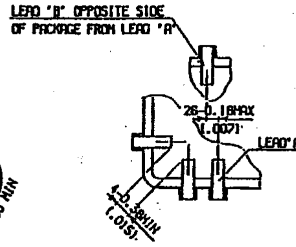


VIEW B



VIEW C





VIEW D

JEDEC OPEN TYPE

NAME		TOLERANCES	DESIGN	CHECKED
52LD QUAD CERPAC' J' (750-550)				
SCALE	MATERIAL		APPROVED	DATE
5 : 1	———			AUG. 27 '90
KYOCERA CORPORATION		KYOTO JAPAN	DWG. No.	QC-052218-J

SPECTRUM
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